



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Tae Heon Lee et al.	) Confirmation No.	8528
Serial No.:	10/763,859	) Art Unit:	2814
Filed:	01/23/2004	) Examiner:	Cao, Phat X.
For:	Semiconductor Package Having Reduced Thickness	)	)

**AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Restriction Requirement mailed March 21, 2005 in relation to the above-identified divisional patent application, please amend the application as follows: